

AMENDMENTS TO THE CLAIMS

Please amend claim 1, 3 and 9, and cancel claims 10-19, as set forth in the listing of claims that follows:

1. (Currently Amended) A microelectronic assembly comprising:
a substrate formed of a transparent material,
an integrated circuit die having an active face facing said substrate and a rear face opposite the active face, said active face including a central region and a perimeter region about the central region,
a plurality of bump interconnections attaching said integrated circuit die to said substrate such that said active face is spaced apart from the substrate by a gap,
a polymeric encapsulant formed of a molded body about said integrated circuit die on said substrate and overlying the rear face, said polymeric encapsulant having sides perpendicular to the substrate and extending within the gap to encapsulate the bump interconnections, and
an optical window defined by said encapsulant within said gap between said central region and said substrate.
2. (Cancelled)

3. (Currently Amended) A microelectronic assembly in accordance with claim 1 wherein ~~the~~ the central region of said die comprises an optical feature adapted for detecting or emitting optical signals through said substrate.

4. (Original) A microelectronic assembly in accordance with claim 1 wherein the polymeric encapsulant is opaque.

5. (Original) A microelectronic assembly in accordance with claim 1 wherein the substrate is formed of glass.

6. (Original) A microelectronic assembly in accordance with claim 1 wherein the polymeric encapsulant is composed of an epoxy polymer and comprises an inorganic particulate filler.

7. (Original) A microelectronic assembly in accordance with claim 1 wherein the substrate is formed of glass and wherein the polymeric encapsulant exhibits a coefficient of thermal expansion between about 6 and 10 ppm per C.

8. (Original) A microelectronic assembly in accordance with claim 1 wherein the bump interconnections are bonded to the die at said perimeter region and to said substrate.

9. (Currently Amended) A microelectronic assembly comprising

a glass substrate,

an integrated circuit die having an active face facing said substrate and a rear face opposite the active face, said active face including a central region and a perimeter region about the central region,

a plurality of solder bump interconnections attaching said integrated circuit die to said substrate, wherein the active face is spaced apart from the substrate by a gap,

an overmolded polymeric encapsulant about said integrated circuit die on said substrate and overlying the rear face of the integrated circuit die, said overmolded polymeric encapsulant having sides perpendicular to the substrate and extending within the gap to encapsulate the bump interconnections, said encapsulant being formed of a polymeric material; and

an optical window defined by said overmolded polymeric encapsulant within said gap between said central region and said substrate.

10-19. (Cancelled)